

[illegible]

09261,681, filing date 3/3/99, A Fill Pattern In Kerf Areas To Prevent Localized Non-Uniformities Of Insulating Layers At Die Corners On Semiconductor Substrates, assigned to the same assignee as the present invention.

A reference to the parent case has been added by Preliminary Amendment to this Divisional Patent Application.

The application is believed to be in condition for allowance. Allowance of the subject Patent Application is therefore respectfully requested.

Respectfully submitted,

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